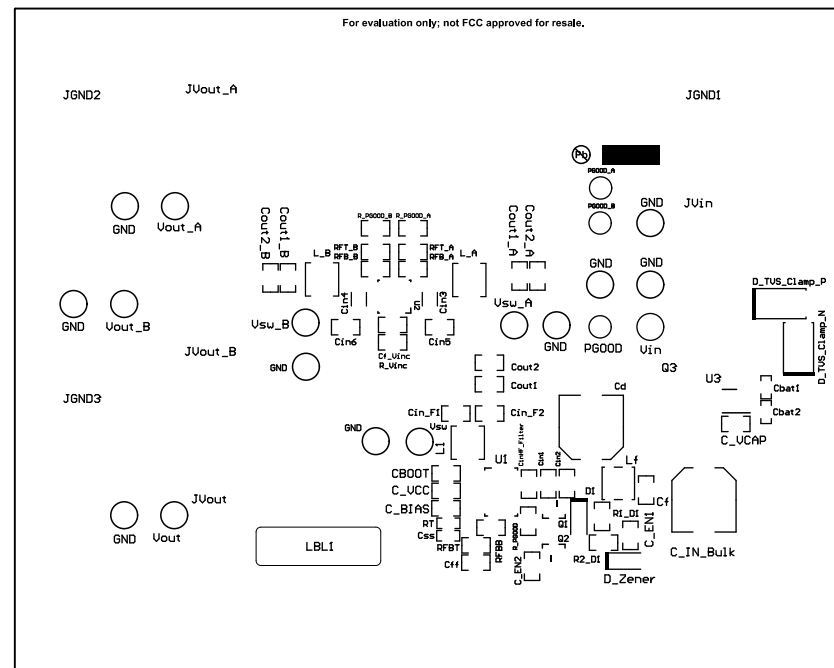
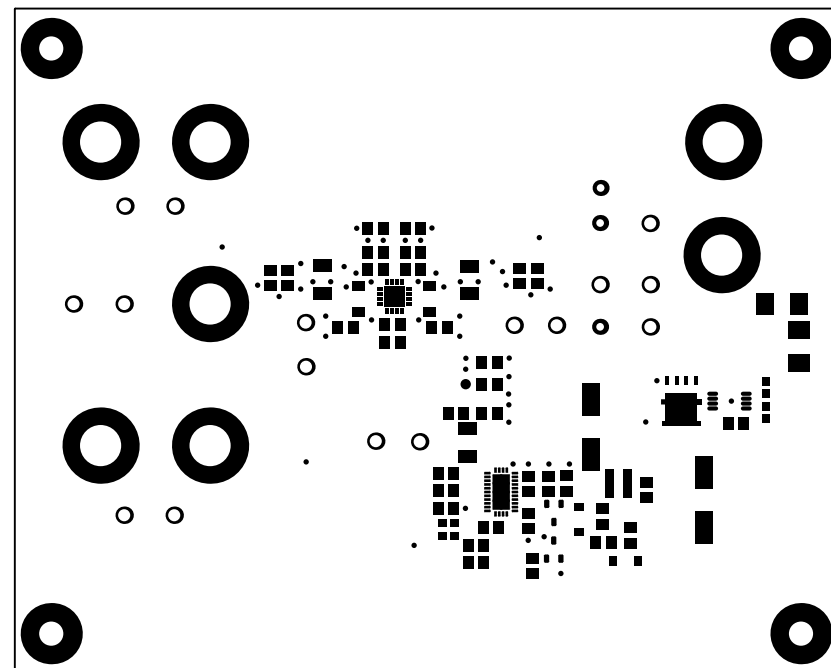


This document can handle board shapes up to 7.9in x 10in, although our panel vendors top out at 7in x 10in.
 To re-size the board shape, do the following:
 Select lines on M1 Board Outline and delete (easy in single layer mode...shift+s)
 Draw a rectangle using lines (example will be for a 4 x 6 board
 Enter Place Line mode (keyboard pl)
 keyboard jo to jump to origin, hit enter
 keyboard j1 to jump to location, set x to 6000, hit enter twice
 keyboard j1 to jump to location, set x to 6000 and y to 4000, hit enter twice
 keyboard j1 to jump to location, set x to 0 and y to 4000, hit enter twice
 keyboard jo to jump to origin, hit enter
 Hit ESC twice to exit place line mode
 Select lines on M1 Board Outline
 Menu Design|Board Shape|Define from Selected Objects (keyboard dsd)

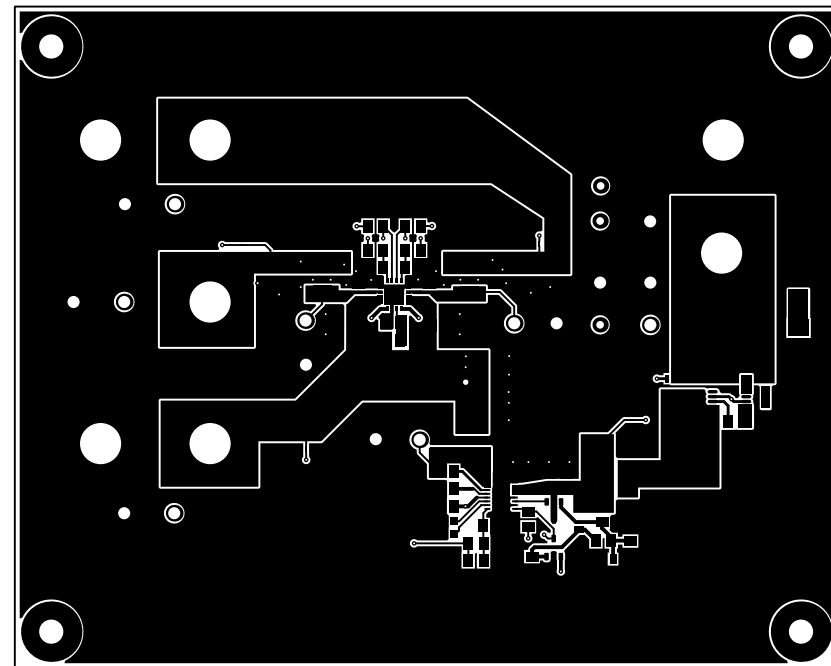
If you re-size the board, don't forget to move the drill table strings on the Drill Drawing Layer...they should be just to the right of your board shape



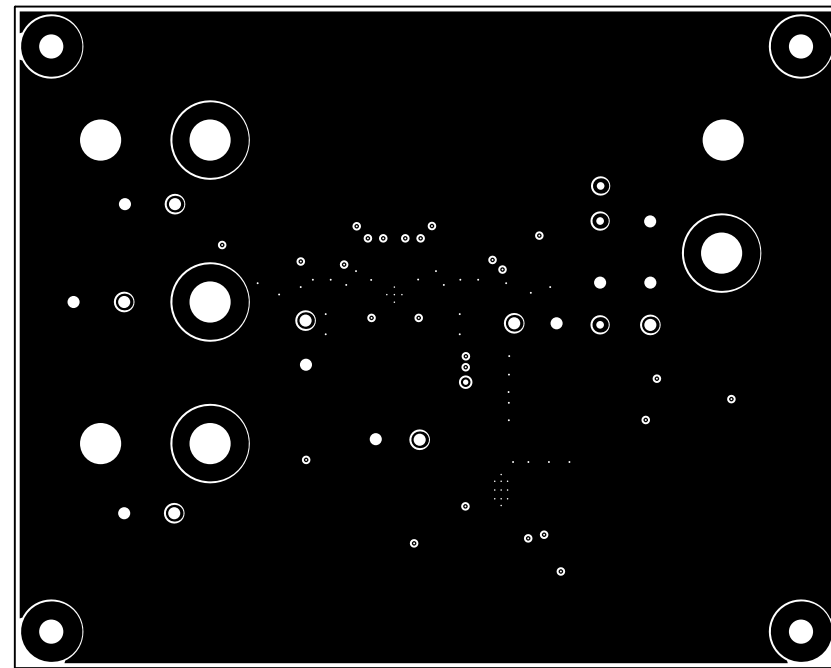
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15023	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP15023		
PLOT NAME = Top Overlay	GENERATED : 10/30/2017 4:45:47 PM	TEXAS INSTRUMENTS	



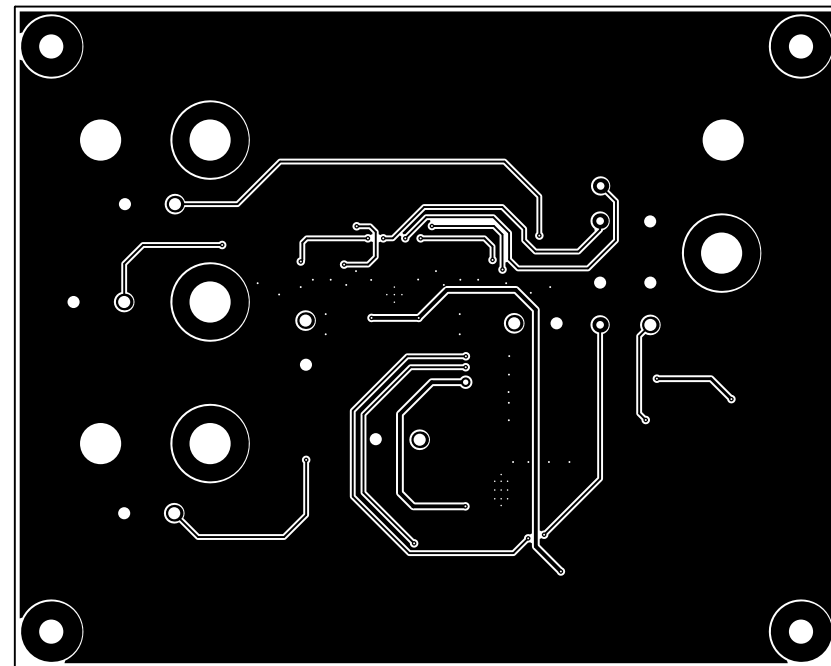
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15023	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP15023		
PLOT NAME = Top Solder Mask	GENERATED : 10/30/2017 4:45:47 PM	TEXAS INSTRUMENTS	



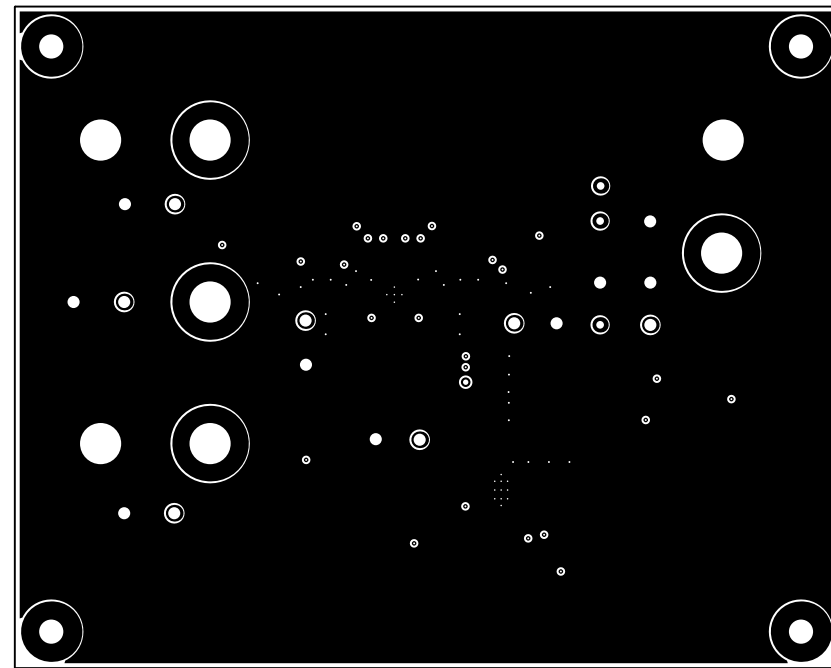
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15023	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP15023		
PLOT NAME = Top Layer	GENERATED : 10/30/2017 4:45:47 PM		TEXAS INSTRUMENTS



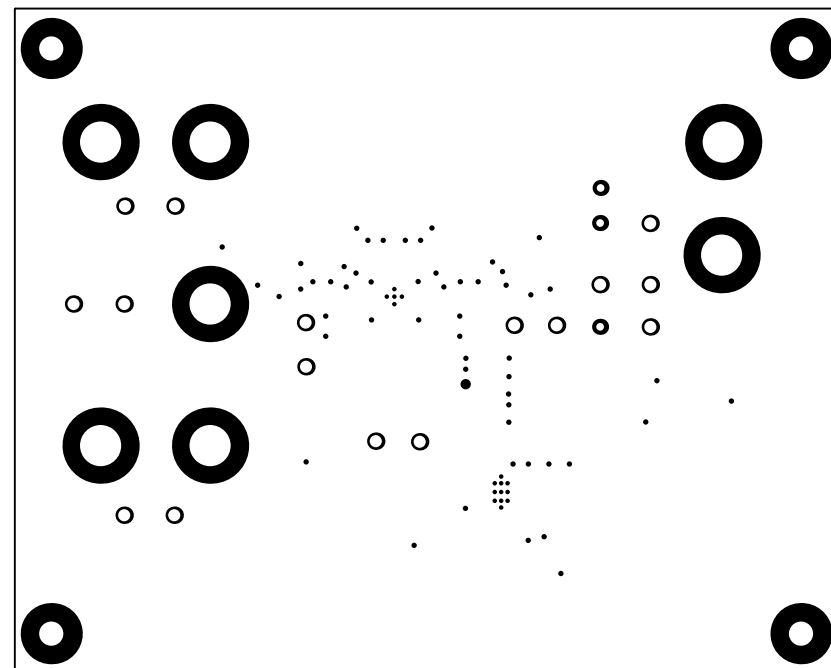
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15023	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP15023		
PLOT NAME = Signal Layer 1	GENERATED : 10/30/2017 4:45:48 PM	TEXAS INSTRUMENTS	



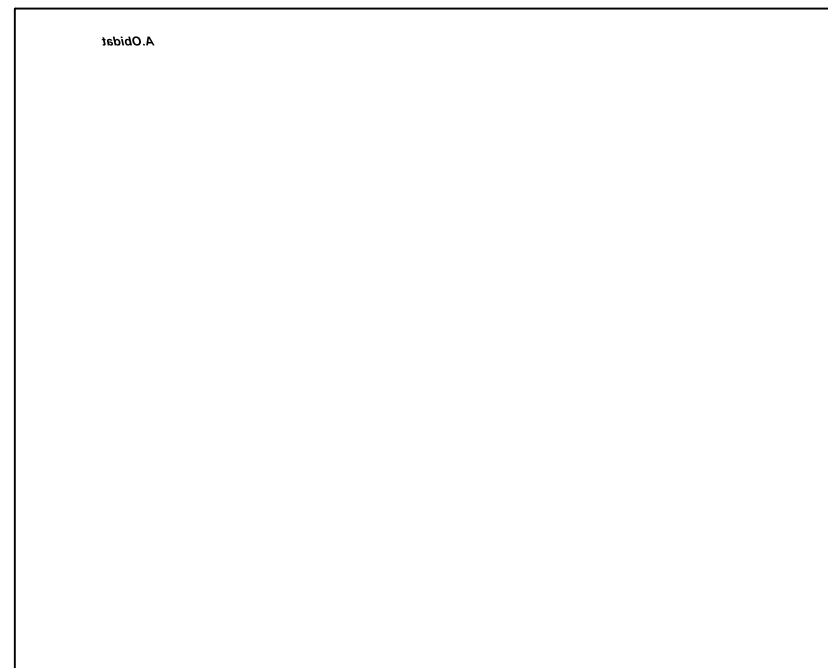
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15023	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP15023		
PLOT NAME = Signal Layer 2	GENERATED : 10/30/2017 4:45:48 PM	TEXAS INSTRUMENTS	



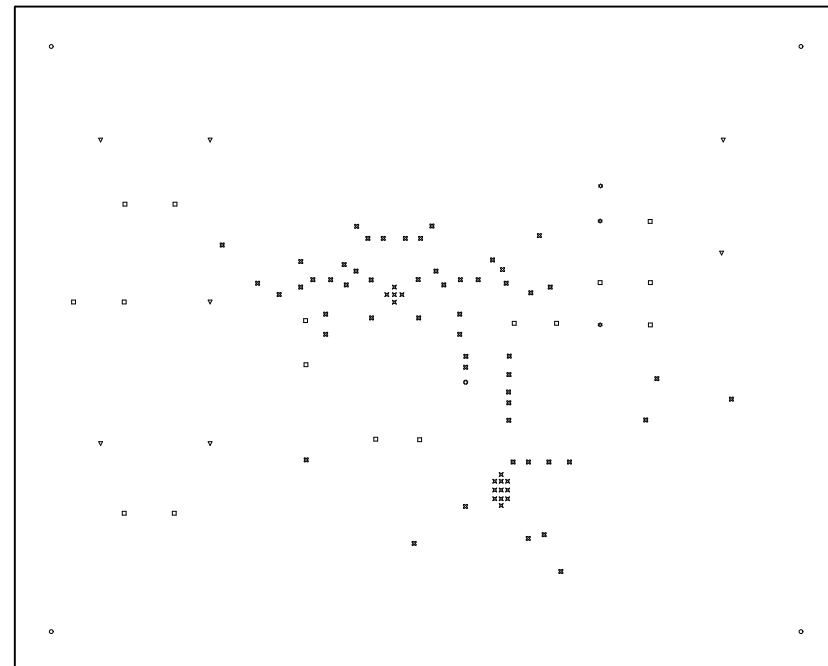
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15023	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP15023		
PLOT NAME = Bottom Layer	GENERATED : 10/30/2017 4:45:48 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15023	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP15023		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/30/2017 4:45:48 PM	TEXAS INSTRUMENTS	

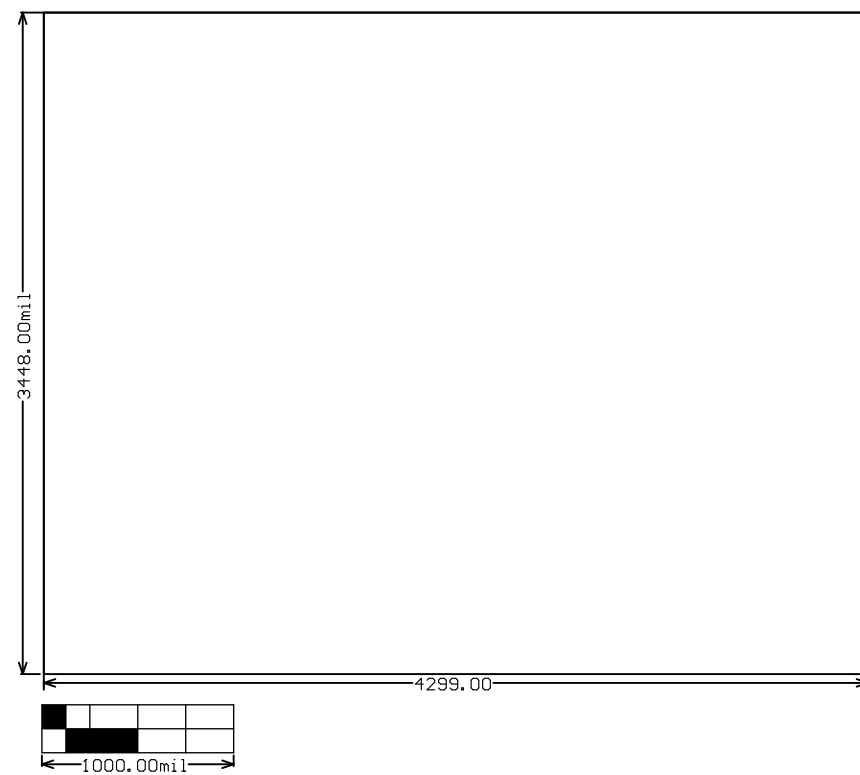


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15023	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP15023		
PLOT NAME = Bottom Overlay	GENERATED : 10/30/2017 4:45:48 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⌘	16	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	54	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	1	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	3	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	16	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
▽	7	214.57mil (5.450mm)	PTH	Round	Top Layer - Bottom Layer	
	101 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15023	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP15023		
PLOT NAME = Drill Drawing	GENERATED : 10/30/2017 4:45:48 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP15023	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP15023		
PLOT NAME = Board Dimensions	GENERATED : 10/30/2017 4:45:49 PM	TEXAS INSTRUMENTS	

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